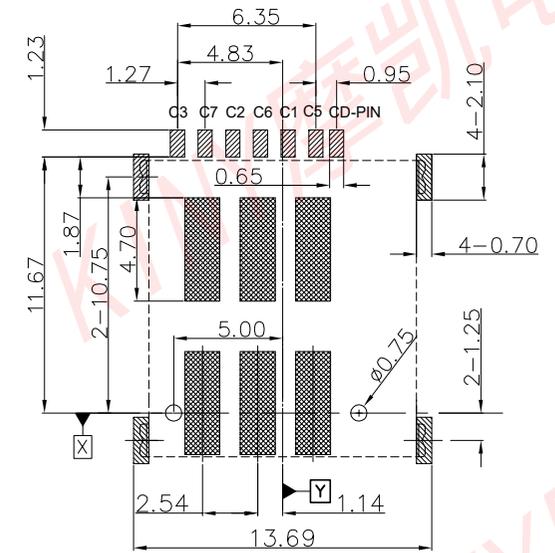
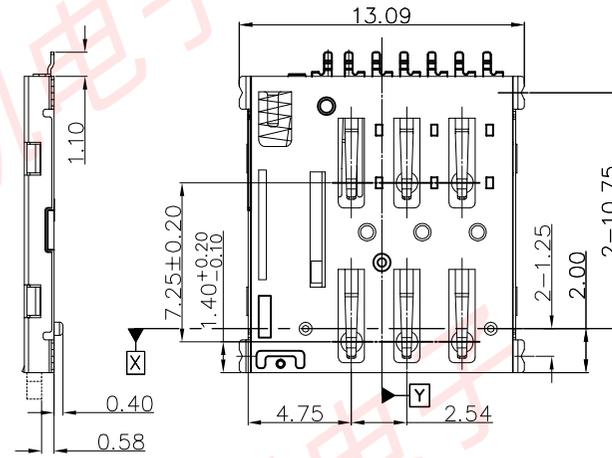
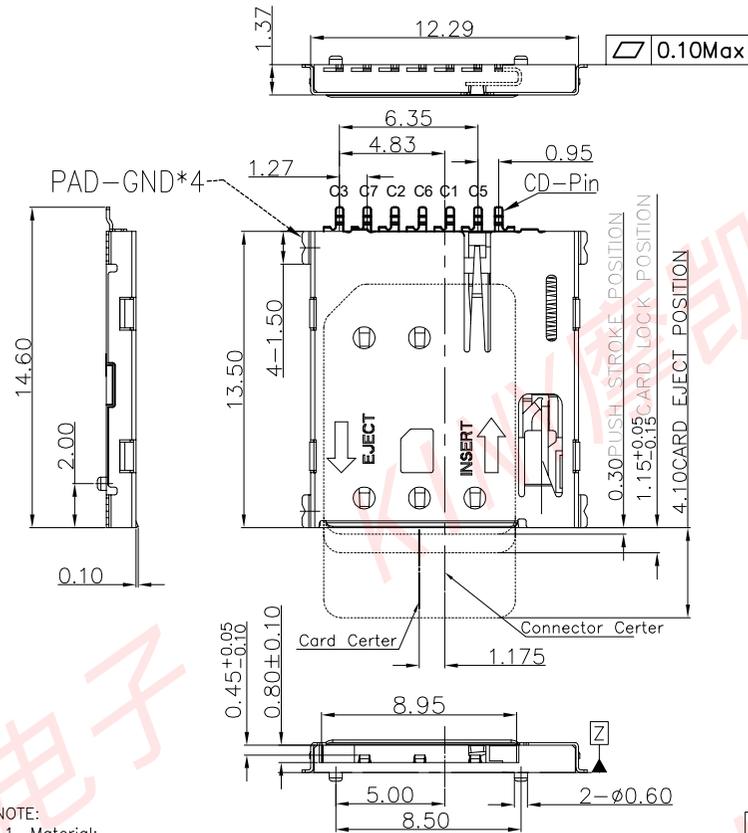


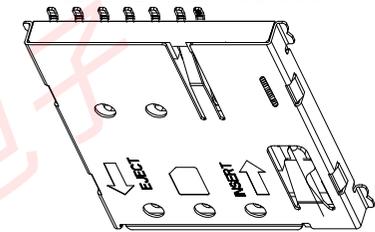
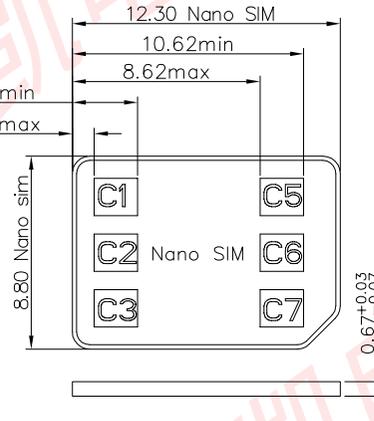
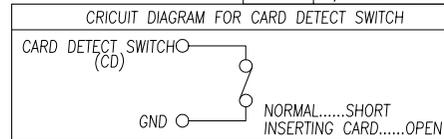
\* 所有原材料, 生产制程, 电镀必须符合H要求



PAD AREA  
 KEEP OUT AREA  
 GND PATTERN ONLY  
 NO COPPER AREA (NO Trace&Via&GND)  
**RECOMMENDED PCB LAYOUT**  
 GENERAL TOLERANCE  $\pm 0.05$

- NOTE:
- Material:
    - 1-1 Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
    - 1-2 Contact: Phosphor Bronze (C5210R-H, T=0.15±0.01mm)
    - 1-3 Cover: SUS301-H T=0.12±0.03mm
  - Plating:
    - 2-1 Contact terminal:
      - Contact area: Gold 1u" Min.
      - Solder area: Gold 0.8u" Min.
      - Underplating: Ni overall 50U" Min.
    - 2-2 Cover:
      - Underplating: Ni overall 50U" Min.
      - Solder area: Gold 0.8u" Min.
  - Specification:
    - 3-1. Current Rating : 0.5mA AC/DC max.
    - 3-2. Voltage Rating : 125V AC/DC
    - 3-3. Ambient Temperature Range : -20°C~+60°C
    - 3-4. Storage Temperature Range : -40°C~+70°C
    - 3-5. Ambient Humidity Range : 95% R.H. Max.
    - 3-6. Contact Resistance: 100m max.
    - 3-7. Insulation Resistance: 1000M min./500VDC
    - 3-8. Mating Cycles: 3000 Insertions

SIM pin assignment	
PIN#	Name
C1	VCC供电电压
C2	RST重置
C3	CLK时钟
C5	GND接地
C6	VPP程序电压
C7	I/O输入输出



	<h2>东莞市摩凯电子有限公司</h2>			
	DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : <b>NANO SIM H1.35 CARD P-P带CD PIN(有柱)</b>	DRAWING: Aaron	DATE: 2023.01.07
	DIMENSION TOLERANCE X.X: ± 0.35 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2'	PRODUCT NO. : NS135-T1151-01	CHECK: DATE:	APPROVED: DATE:
	DRAWING NO. : D-NS135-T1151-01	SCALE: 1:1 	DWG ID: C D REV.: X0	PAGE: 1 OF 1

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
X0	----	NEW RELEASE	Aaron	2023.01.07